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Universal serial bus interfaces for data and power –
Part 1-2: Common components – USB Power Delivery specification

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**Universal serial bus interfaces for data and power –
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INTERNATIONAL
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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

Part 1-2: Common components – USB Power Delivery specification

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This second edition cancels and replaces the first edition published in 2016 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this standard is based on the following documents:

CDV	Report on voting
100/2820/CDV	100/2906/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.0a and ECNs as of 2 August 2016.

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Universal Serial Bus
Power Delivery Specification

Revision 3.0, V1.0a. 25 March 2016 + ECNs 2 August 2016

Editors

Bob Dunstan	Intel Corporation
Richard Petrie	DisplayLink

Contributors

Charles Wang	ACON, Advanced-Connectek, Inc.
Conrad Choy	ACON, Advanced-Connectek, Inc.
Steve Sedio	ACON, Advanced-Connectek, Inc.
Vicky Chuang	ACON, Advanced-Connectek, Inc.
Joseph Scanlon	Advanced Micro Devices
Howard Chang	Allion Labs, Inc.
Greg Stewart	Analogix Semiconductor, Inc.
Mehran Badii	Analogix Semiconductor, Inc.
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Corey Lange	Apple
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Shawn Meng	Bizlink Technology Inc.
Tiffany Hsiao	Bizlink Technology, Inc.
Weichung Ooi	Bizlink Technology, Inc.
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Matteo Casalin	Canova Tech
Nicola Scantamburlo	Canova Tech

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Jagadeesan Raj	Cypress Semiconductor	
Pradeep Bajpai	Cypress Semiconductor	
Rushil Kadakia	Cypress Semiconductor	
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Sumeet Gupta	Cypress Semiconductor	
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Gary Verdun	Dell Inc.	
Merle Wood	Dell Inc.	
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Siddhartha Reddy	Dell Inc.	
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Jason Young	DisplayLink	
Peter Burgers	DisplayLink	
Richard Petrie	DisplayLink	PD Chair/Device Policy Lead
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Chuck Trefts	Ellisys	
Emmanuel Durin	Ellisys	
Mario Pasquali	Ellisys	
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Jack Yang	Etron Technology, Inc.	
Richard Crisp	Etron Technology, Inc.	
Shyanjia Chen	Etron Technology, Inc.	
TsungTa Lu	Etron Technology, Inc.	
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Oscar Freitas	Fairchild Semiconductor	
Souhib Harb	Fairchild Semiconductor	
AJ Yang	Foxconn / Hon Hai	
Fred Fons	Foxconn / Hon Hai	
Steve Sedio	Foxconn / Hon Hai	
Terry Little	Foxconn / Hon Hai	
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Rajaraman V	Granite River Labs	
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Robin Castell	Hewlett Packard	
Roger Benson	Hewlett Packard	
Ron Schooley	Hewlett Packard	
Vaibhav Malik	Hewlett Packard	
Walter Fry	Hewlett Packard	
Bob Dunstan	Intel Corporation	PD Chair/Protocol WG Lead
Brad Saunders	Intel Corporation	
Chee Lim Nge	Intel Corporation	
Christine Krause	Intel Corporation	
Dan Froelich	Intel Corporation	
David Harriman	Intel Corporation	
David Hines	Intel Corporation	
David Thompson	Intel Corporation	
Guobin Liu	Intel Corporation	
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Jervis Lin	Intel Corporation	
John Howard	Intel Corporation	
Karthi Vadivelu	Intel Corporation	
Leo Heiland	Intel Corporation	
Maarit Harkonen	Intel Corporation	
Nge Chee Lim	Intel Corporation	
Paul Durley	Intel Corporation	
Rahman Ismail	Intel Corporation	System Policy Lead
Ronald Swartz	Intel Corporation	
Sarah Sharp	Intel Corporation	
Scott Brenden	Intel Corporation	
Sridharan Ranganathan	Intel Corporation	
Steve McGowan	Intel Corporation	
Tim McKee	Intel Corporation	PD Chair/Compliance Lead
Toby Opferman	Intel Corporation	
Kenta Minejima	Japan Aviation Electronics Industry Ltd. (JAE)	
Mark Saubert	Japan Aviation Electronics Industry Ltd. (JAE)	
Toshio Shimoyama	Japan Aviation Electronics Industry Ltd. (JAE)	
Brian Fetz	Keysight Technologies Inc.	

Babu Mailachalam	Lattice Semiconductor Corp
Gianluca Mariani	Lattice Semiconductor Corp
Joel Coplen	Lattice Semiconductor Corp
Thomas Watza	Lattice Semiconductor Corp
Vesa Lauri	Lattice Semiconductor Corp
Daniel H Jacobs	LeCroy Corporation
Jake Jacobs	LeCroy Corporation
Kimberley McKay	LeCroy Corporation
Mike Micheletti	LeCroy Corporation
Roy Chestnut	LeCroy Corporation
Phil Jakes	Lenovo
Dave Thompson	LSI Corporation
Alan Kinningham	Luxshare-ICT
Daniel Chen	Luxshare-ICT
Josue Castillo	Luxshare-ICT
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Geert Knapen	MCCI Corporation
Terry Moore	MCCI Corporation
Velmurugan Selvaraj	MCCI Corporation
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Dave Perchlik	Microchip Technology Inc.
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Pat Crowe	MQP Electronics Ltd.	
Sten Carlsen	MQP Electronics Ltd.	
Frank Borngräber	Nokia Corporation	
Kai Inha	Nokia Corporation	
Pekka Leinonen	Nokia Corporation	
Richard Petrie	Nokia Corporation	PD Vice-Chair/Device Policy Lead
Sten Carlsen	Nokia Corporation	Physical Layer WG Lead
Abhijeet Kulkarni	NXP Semiconductors	
Ahmad Yazdi	NXP Semiconductors	
Bart Vertenten	NXP Semiconductors	
Dong Nguyen	NXP Semiconductors	
Guru Prasad	NXP Semiconductors	
Ken Jaramillo	NXP Semiconductors	
Krishnan TN	NXP Semiconductors	
Michael Joehren	NXP Semiconductors	
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Rod Whitby	NXP Semiconductors	
Vijendra Kuroodi	NXP Semiconductors	
Robert Heaton	Obsidian Technology	
Bryan McCoy	ON Semiconductor	
Cor Voorwinden	ON Semiconductor	
Edward Berrios	ON Semiconductor	
Tom Duffy	ON Semiconductor	Power Supply WG Lead
Craig Wiley	Parade Technologies Inc.	
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Atsushi Mitamura	Renesas Electronics Corp.	
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Philip Leung	Renesas Electronics Corp.	
Steve Roux	Renesas Electronics Corp.	

Tetsu Sato	Renesas Electronics Corp.	
Heinz Wei	Richtek Technology Corporation	
Tatsuya Irisawa	Ricoh Company Ltd.	
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Chris Lin	Rohm Co. Ltd.	
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Ruben Balbuena	Rohm Co. Ltd.	
Takashi Sato	Rohm Co. Ltd.	
Vijendra Kuroodi	Rohm Co. Ltd.	
Yusuke Kondo	Rohm Co. Ltd.	
Matti Kulmala	Salcomp Plc	
Toni Lehimo	Salcomp Plc	
Tong Kim	Samsung Electronics Co. Ltd.	
Alvin Cox	Seagate Technology LLC	Cab Con WG Lead
John Hein	Seagate Technology LLC	
Marc Noblitt	Seagate Technology LLC	
Ronald Rueckert	Seagate Technology LLC	
Tony Priborsky	Seagate Technology LLC	
John Sisto	SMSC	
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Richard Wahler	SMSC	
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Tim Knowlton	SMSC	
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Nathalie Ballot	ST-Microelectronics	
Pascal Legrand	ST-Microelectronics	
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Kimberley McKay	Teledyne-LeCroy	
Matthew Dunn	Teledyne-LeCroy	

Tony Minchell	Teledyne-LeCroy	
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Terrance Shih	VIA Technologies, Inc.	
Charles Neumann	Western Digital Technologies, Inc.	
Curtis Stevens	Western Digital Technologies, Inc.	
John Maroney	Western Digital Technologies, Inc.	

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2.0	1.1	Including errata through 7-May 2015	7 May 2015
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.0a + ECNs	This markup contains the following ECNs applied to the Revision 3.0 V1.0a specification text: • Applicability of Messages • DRP and DRD bits in Capabilities Messages • Wait Timing • iCapChange Removal • vSafe5V Voltage Range Clarification • Wait Timing • NoResponseTimer • Specification Revision Interoperability	2 August 2016